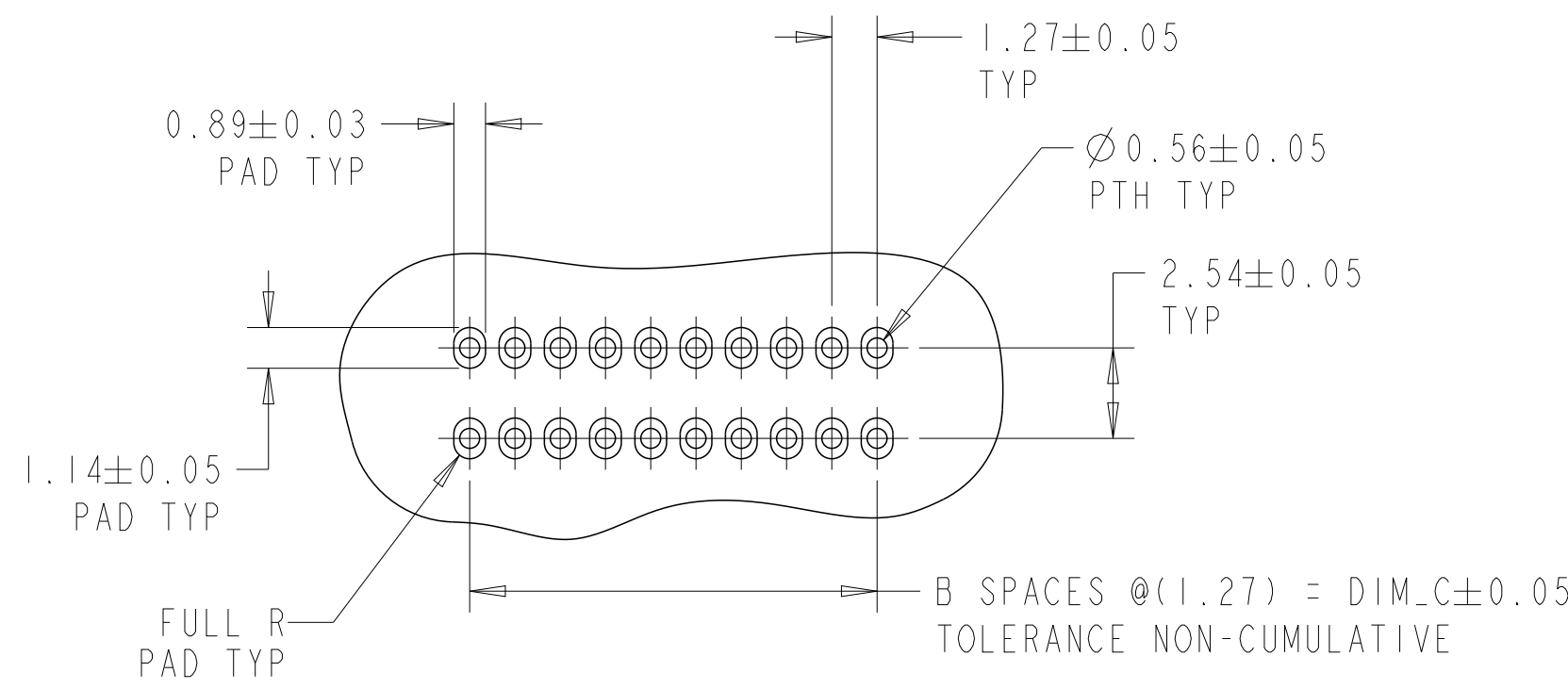
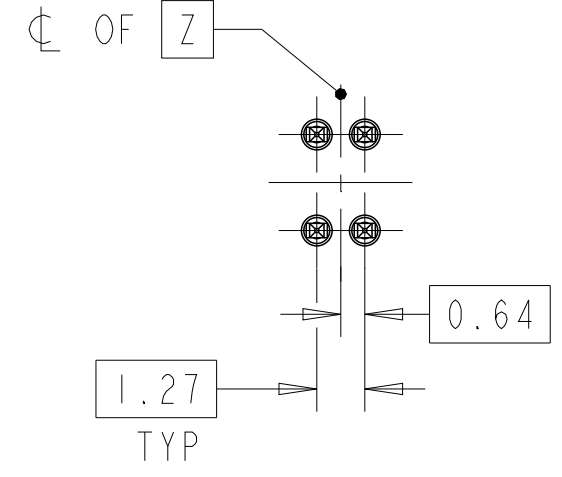
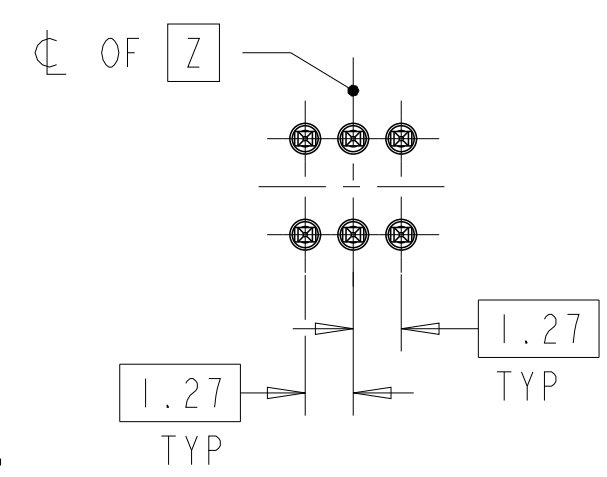


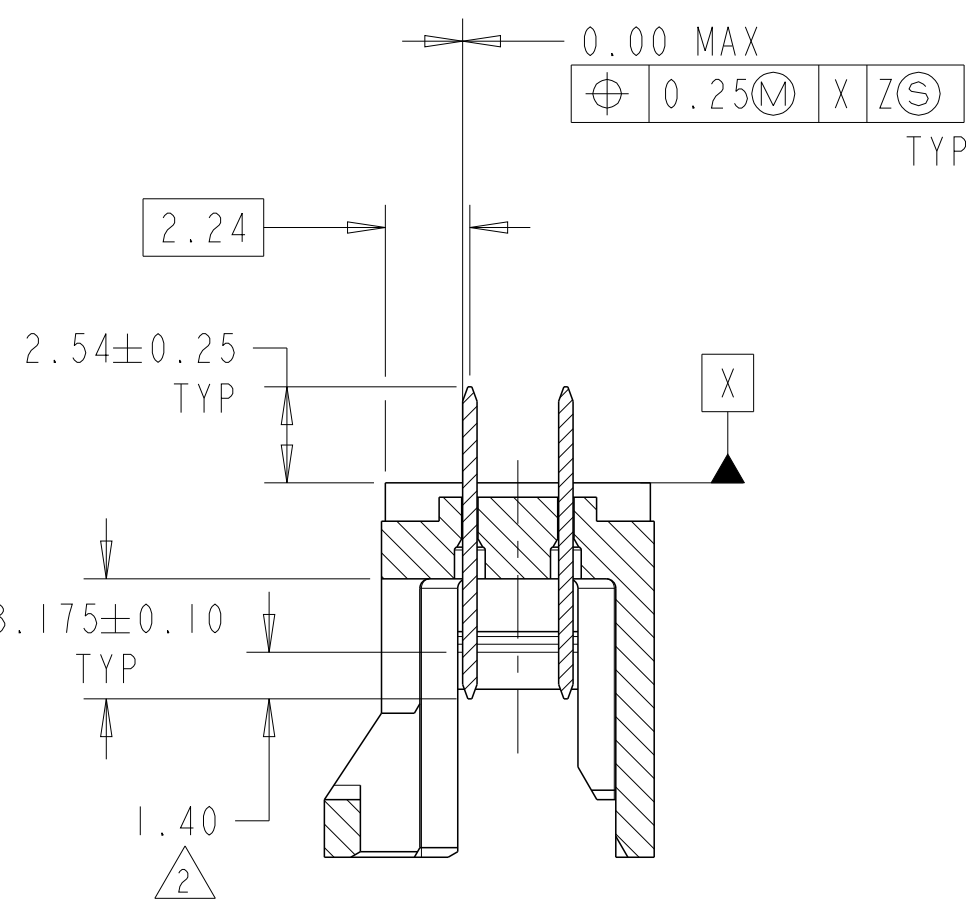
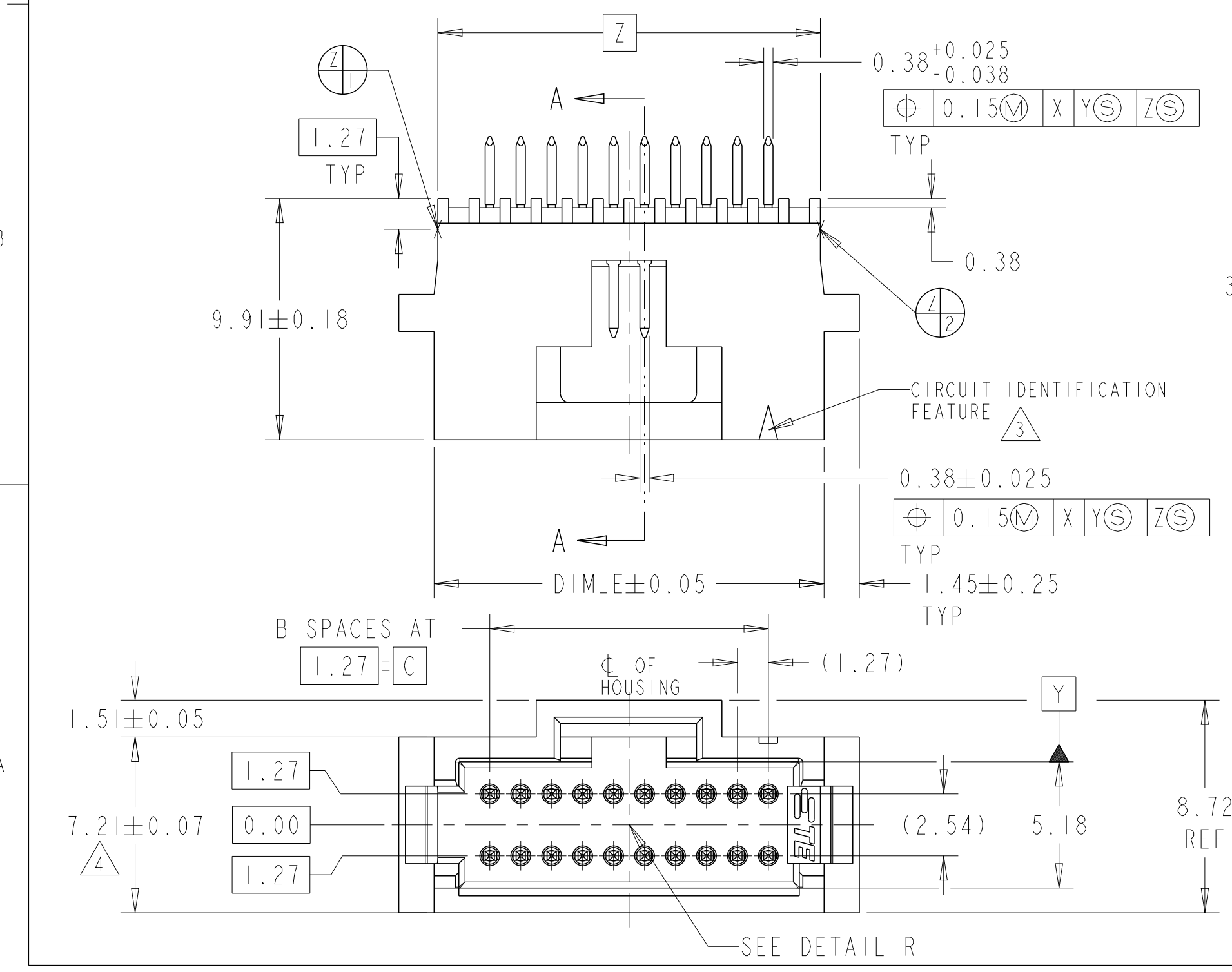
- 1 CONTACT AREA PLATED WITH 0.76µm MIN GOLD; SOLDER TAILS PLATED WITH 3.81µm MIN TIN-LEAD, ALL OVER 1.27µm MIN NICKEL.
- 2 POINT OF MEASUREMENT FOR PLATING THICKNESS.
- 3 CIRCUIT IDENTIFICATION FEATURE OMITTED ON 8,10,12 AND 14 POSN HEADER ASSEMBLIES.
- 4 DIMENSION APPLIES AT BASE OF SHROUD.
- 5 NOTE DELETED.
- 6 NOTE DELETED.
- 7 CONTACT AREA PLATED WITH 0.76µm MIN. GOLD; SOLDER TAILS PLATED WITH 3.81µm MIN TIN; ALL OVER 1.27µm MIN NICKEL.
- 8 FINISH: 0.025µm MIN GOLD ON GOLD PLATED AREA. 3.81-6.35µm MATTE TIN-LEAD ON TIN PLATED AREA. UNDER PLATING TO BE 1.27-2.54µm NICKEL ON ENTIRE CONTACT.
- 9 FINISH: 0.025µm MIN GOLD ON GOLD PLATED AREA. 3.81-6.35µm MATTE TIN ON TIN PLATED AREA. UNDER PLATING TO BE 1.27-2.54µm NICKEL ON ENTIRE CONTACT.
- 10 NOTE DELETED.
- 11 NOTE DELETED.
- 12 MATERIAL : HOUSING : LCP
COLOR : BLACK
POST : COPPER ALLOY.



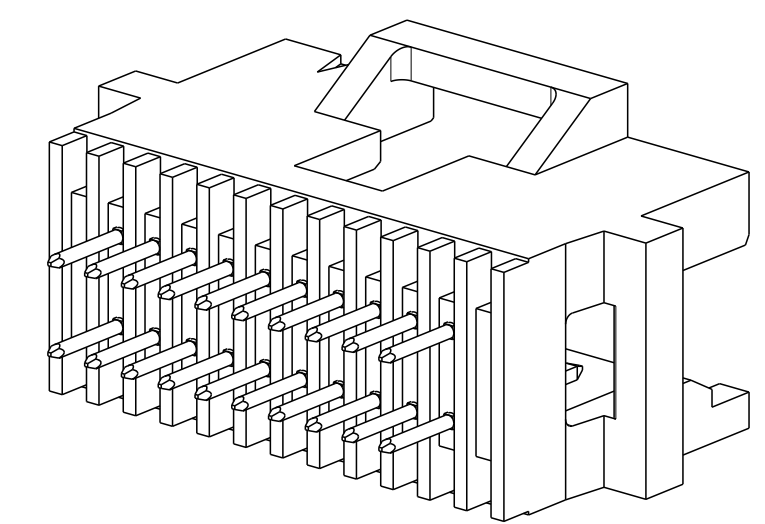
RECOMMENDED PC BOARD LAYOUT



DETAIL R



SECTION A-A



THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN: RAVI.S
CHK: J. OLSON
APVD: J. OLSON

18MAY2017
18MAY2017
18MAY2017

PRODUCT SPEC
108-1093
APPLICATION SPEC
114-25031

WEIGHT: -

CUSTOMER DRAWING

TE Connectivity

NAME: HEADER ASSEMBLY, VERTICAL, DOUBLE ROW, W/SIDE & END LATCHES, AMPMODU System 50

SIZE: A2
CAGE CODE: -
DRAWING NO: C-104068

RESTRICTED TO: -

SCALE: 5:1
SHEET: 1 OF 2
REV: R1

4		3		2		1									
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							-	SEE SHEET 1			-	-	-		